

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Appl. No. : 10/537,666 Confirmation No. 6346
Applicant : Chris WYLAND
Filed : June 6, 2005
TC/A.U. : 2811
Examiner : Ajay Arora

Docket No. : US02 0512 US
Customer No. : 24738

Title: HIGH DENSITY PACKAGE INTERCONNECT WIRE
BOND STRIP LINE AND METHOD THEREFOR

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE & AMENDMENT

Sir:

In response to the Office Action of May 17, 2006, Applicant requests consideration of the following:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 5 of this paper.

Remarks/Arguments begin on page 8 of this paper.